

2818



Applicant : Haruo Hyodo et al.
 Serial No. : 09/963,839
 Filed : September 26, 2001
 Title : SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF

Art Unit : 2818
 Examiner : Quoc Dinh Hoang

Commissioner for Patents
 Washington, D.C. 20231

RESPONSE TO OFFICE ACTION DATED SEPTEMBER 12, 2002

REMARKS

Claims 1-7 are pending.

In view of the following remarks, the applicants respectfully request withdrawal of each of the rejections and allowance of the application.

Claim Rejections 35 USC § 102

Claims 1-7 have been rejected under 35 U.S.C. § 102(e) as anticipated by Mizuno et al.

Claim 1 recites a semiconductor device that includes a "glass plate" that covers a circuit element forming a hollow airtight portion between a supporting substrate and the glass plate. The use of a "glass plate" facilitates the visual inspection and also the removal of the semiconductor device if a device fabrication failure has occurred. (see page 3, lines 11-16 of the application) The background section of the application points out that in prior art devices use a non-glass plate (e.g. ceramic) which prevents the visual inspection of the device once the device is sealed. (see page 2, lines 5-10 of the application)

Mizuno discloses a device that includes a main body 2 and a cap 6. However, the cap is formed from ceramic and according to one embodiment, alumina is used (see column 4, lines 37-42), in contrast to a "glass plate" as recited in claim 1. Thus, Mizuno fails to teach or suggest a

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